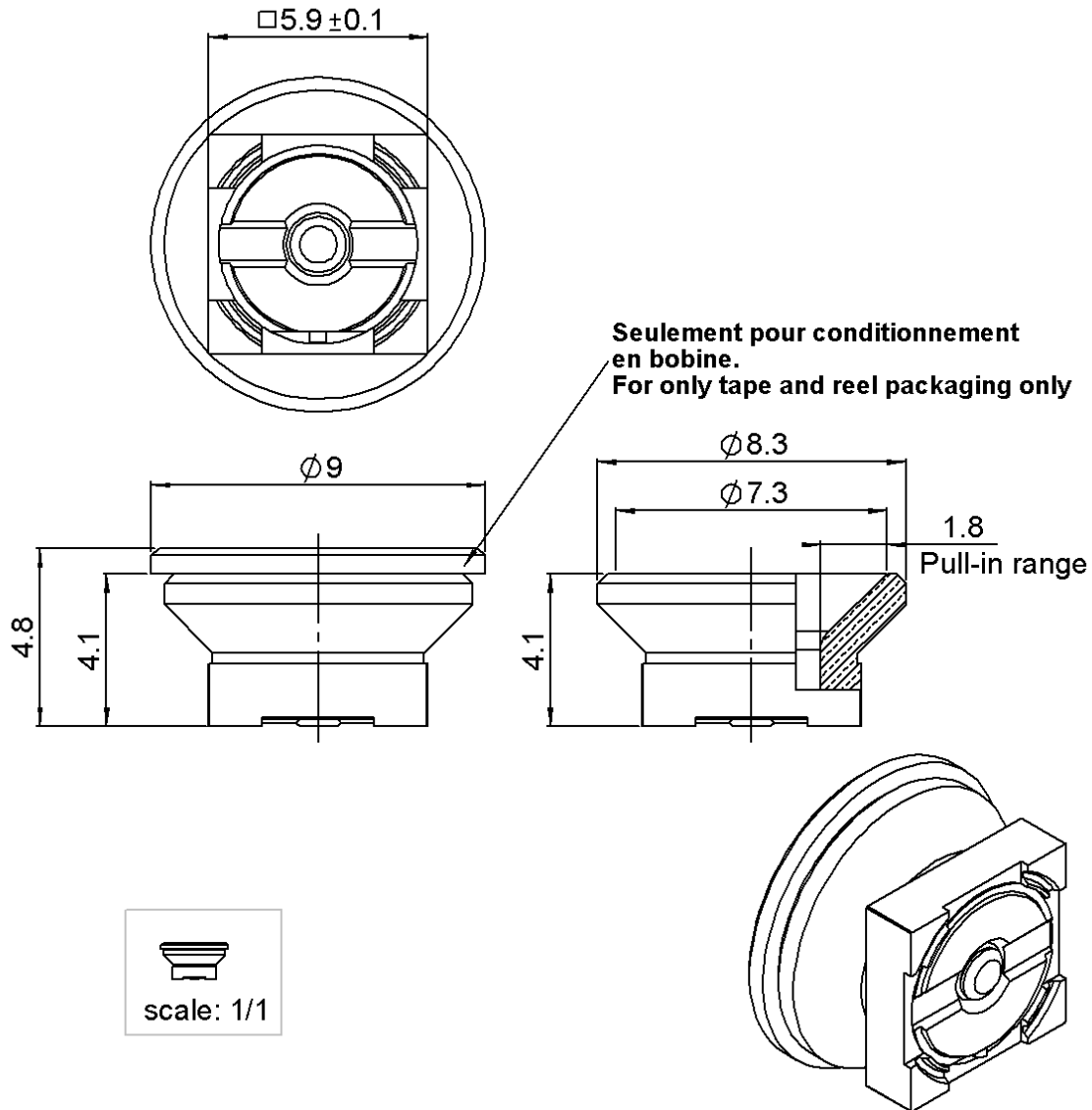


SMT JACK RECEPTACLE

R223.424.870

REEL OF 750

Series : MMBX



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
BODY	BRASS	NPGR
CENTER CONTACT	BRASS	NPGR
OUTER CONTACT		
INSULATOR	LIQUID CRYSTAL POLYMER	
GASKET		
OTHERS PARTS	PTFE	
-	-	-
-	-	-

Issue : 0851 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



SMT JACK RECEPTACLE

R223.424.870

REEL OF 750

Series : MMBX

PACKAGING

SPECIFICATION

Standard	Unit	Other
750	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance	50 Ω
Frequency	0-12.4 GHz
VSWR	1.065* + 0,0000 x F(GHz) Maxi
Insertion loss	0.12 √F(GHz) dB Maxi
RF leakage	- (100** - F(GHz)) dB Maxi
Voltage rating	330 Veff Maxi
Dielectric withstanding voltage	1000 Veff mini
Insulation resistance	1000 MΩ mini

Operating temperature	-55/+155 ° C
Hermetic seal	NA Atm.cm3/s
Panel leakage	NA

OTHER CHARACTERISTICS

Assembly instruction

Others :

**to 6 GHz

**interface MMBX only up to 2.5GHz

PCB to PCB -45dB up to 2.5 GHz

MECHANICAL CHARACTERISTICS

Center contact retention	
Axial force – Mating end	10 N mini
Axial force – Opposite end	10 N mini
Torque	NA N.cm mini
Recommended torque	
Mating	NA N.cm
Panel nut	NA N.cm
Mating life	100 Cycles mini
Weight	0,8900 g

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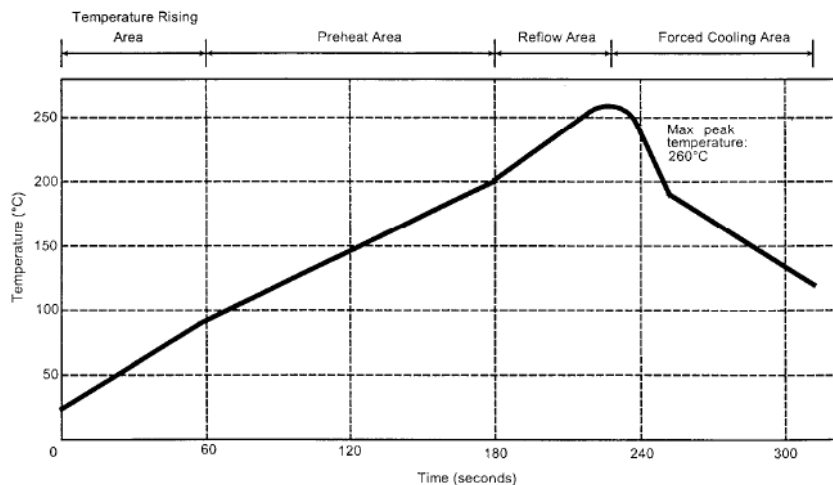
REEL OF 750

Series : MMBX

SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
3. Soldering by infra-red reflow.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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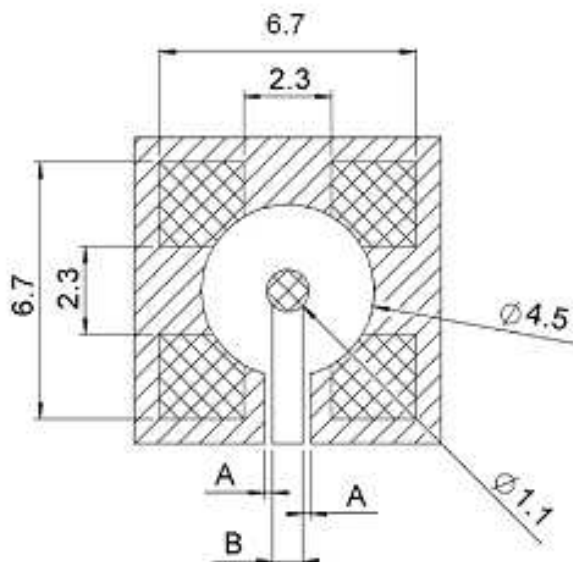
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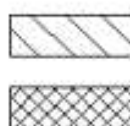
REEL OF 750

Series : MMBX

MMBX SERIES INFORMATIONS



COPLANAR LINE
 Pattern and signal are on the same side
 The material of PCB is epoxy resin (FR4) (Er = 4.6)
 The solder resist should be printed
 Except for the land pattern on the PCB



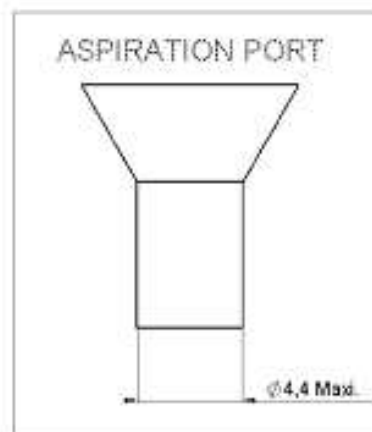
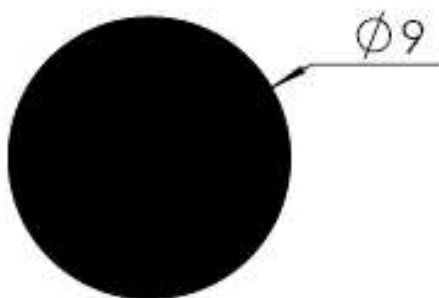
Pattern

Land for solder paste

APPLICATION 75Ω	
WITH B = 0,55mm	
PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1,6	0,375

APPLICATION 50Ω	
WITH B = 1,2mm	
PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
1,6	0,210

SHADOW FOR VIDEO CAMERA



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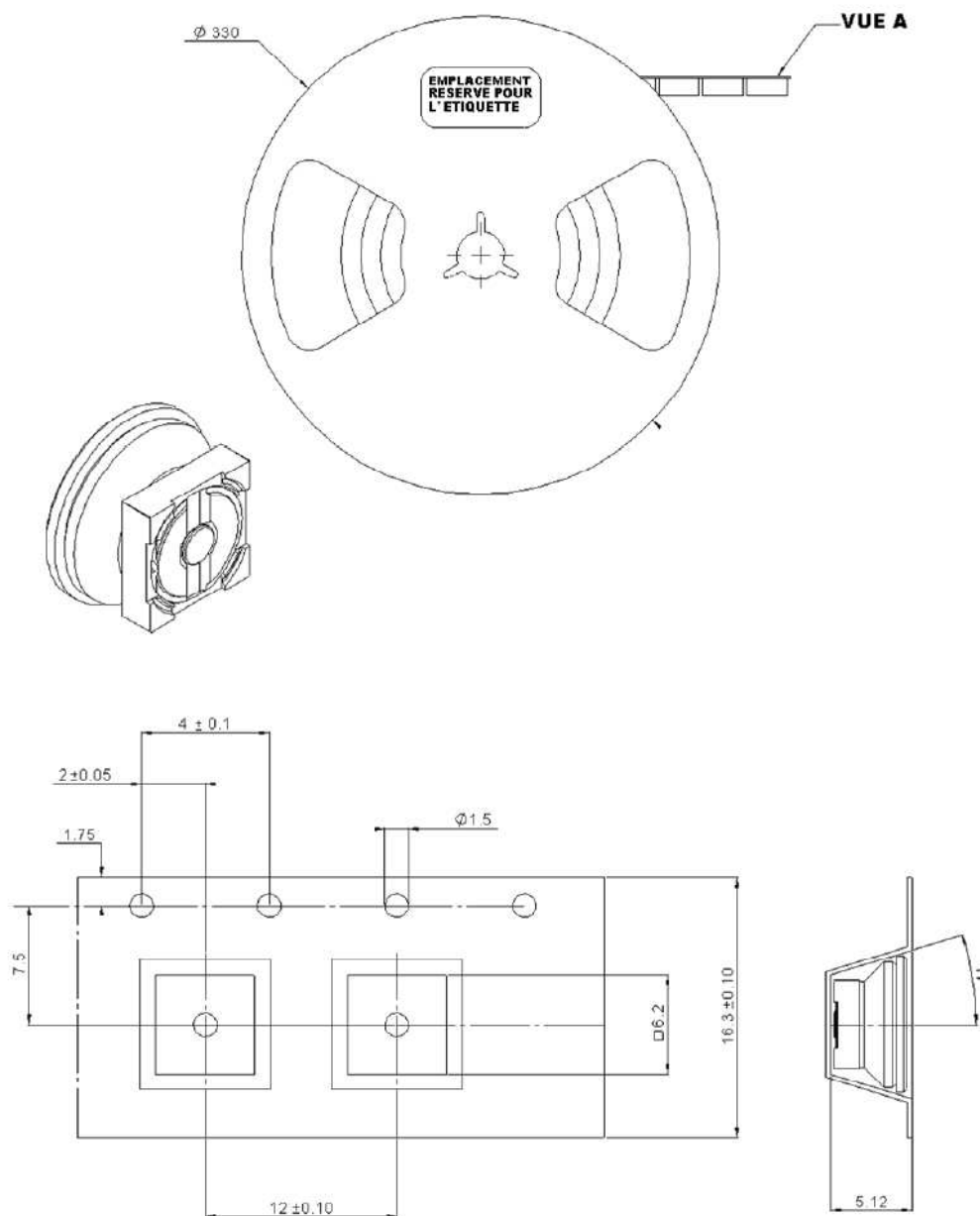
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REEL OF 750

Series : MMBX

MMBX SERIES INFORMATIONS



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